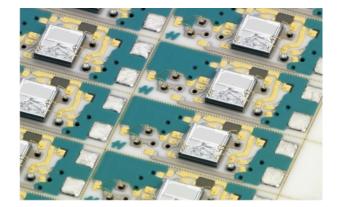


DIE BONDING

TECHNOLOGY

CHIPS SIZE:	SIDE 0.2 - 10mm	SUBSTRATES:	THICK FILM CERAMIC
		FR4, Fr5, G10, G11, ROGERS FLEX, RIGID FLEX, IMS	
TRACEABILITY:	WAFER MAPPING		PYREX
POSITIONING ACCURACY:	STANDARD +/- 30μm	ADHESIVES:	CONDUCTIVE
	Specific +/- 15µm		NON-CONDUCTIVE
			SILICONE
PACKAGING:	WAFER UP TO 8"	ADHESIVE APPLICATION:	STAMPING
	WAFFLE PACK 2 - 4"		DISPENSING
	Gelpack		SILK SCREEN PRINTING



HYBRID SA IS ABLE TO BOND CHIPS OF DIFFERENT SIZE AND THICKNESS ON DIFFERENT TYPES OF SUBSTRATES. POSITIONING ACCURACY AND OTHER PRODUCT SPECIFICATIONS ARE DETERMINED IN COLLABORATION WITH THE CLIENT.

